

What is claimed is:

1. A method of mounting an electronic part,  
comprising the steps of:  
applying flux-fill, which acts as flux and under-filling resin, on a surface  
of a mount board, in which electrodes are formed;  
respectively connecting solder bumps of the electronic part with the  
electrodes; and  
simultaneously filling a gap between the electronic part and the mount  
board with the flux-fill,  
wherein the solder bumps are made contact with the electrodes, and  
ultrasonic vibration energy is applied to contact portions of the solder bumps  
and the electrodes in said connecting step.
2. The method according to claim 1,  
wherein the electronic part is ultrasonic-vibrated so as to connect the  
solder bumps with the electrodes in said connecting step.
3. The method according to claim 1,  
wherein the flux-fill includes fillers.
4. The method according to claim 1,  
further comprising the step of heating the flux-fill to solidify.
5. The method according to claim 1,  
wherein the flux-fill comprises:  
a main agent made from resin;  
a hardening agent for hardening the resin;  
a hardening accelerator;

organic acid acting as flux; and  
fillers.

6. A flux-fill,  
comprising:  
a main agent made from resin;  
a hardening agent for hardening the resin;  
a hardening accelerator;  
organic acid acting as flux; and  
fillers.